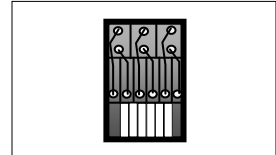


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Huawei LTE-FDD Baseband Unit WD2BBUC-HERT BBU Model BBU3900

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TABLE OF CONTENTS

EXECUTIVE SUMMARY	6
Active/Passive Component Summary	6
Important Note:	6
CHAPTER 1: HUAWEI TECHNOLOGIES DBS3900 BTS SYSTEM	7
Overview of DBS3900 Product Offering	7
CHAPTER 2: BSBC MECHANICAL ANALYSIS	11
Mechanical Analysis.....	11
BSBC Backplane PCB.....	15
CHAPTER 3: FAN UNIT (UBFA)	18
CHAPTER 4: UPEUC	24
CHAPTER 5: LTE CONFIGURATION	33
CHAPTER 6: LMPT	34
CHAPTER 7: LBBP	53
APPENDIX A - PASSIVE CASE SIZE ANALYSIS.....	61
APPENDIX B - ACTIVE COMPONENT MARKET SHARE ANALYSIS	65

TABLES

Table 1: BSBC PCB Bill of Materials, Top	17
Table 2: BSBC PCB Bill of Materials, Bottom	17
Table 3: Fan Unit Bill of Materials.....	20
Table 4: Fan Unit PCB, Top Bill of Materials	23
Table 5: Fan Unit PCB, Bottom Bill of Materials	23
Table 6: UPEU Ethernet PCB Bill of Materials	27
Table 7: UPEU Main PCB Area A Bill of Materials.....	31
Table 8: UPEU Main PCB Area B Bill of Materials.....	32
Table 9: LMPT Top View Bill of Materials	43
Table 10: LMPT Top View Area A Bill of Materials	47
Table 11: LMPT Top View Area B Bill of Materials	48
Table 12: LMPT Bottom View Area B Bill of Materials	49
Table 13: LMPT Top View Area C Bill of Materials	50
Table 14: LMPT Bottom View Area C Bill of Materials	50
Table 15: LMPT Bottom View Bill of Materials.....	51
Table 16: LBBP Variant Specifications.....	53
Table 17: LBBP Variant Maximum Data Rate Support	54
Table 18: LBBP Top View Bill of Materials.....	58
Table 19: LBBP Bottom View Bill of Materials.....	60
Table 20: Passive Component Case Size Distribution by System Subsection	62
Table 21: Identified Passive Component Supplier Distribution by System Subsection.....	63
Table 22: Active/Passive Component Distribution by System Subsection.....	64
Table 23: Active Semiconductor/Component Vendor Distribution by System Subsection	66

EXHIBITS

Exhibit 1: BTS3900 DBS3900	7
Exhibit 2: BBU3900 BSBC Unit.....	8
Exhibit 3: BBU3900 Logical Structure for LTE Configuration.....	8
Exhibit 4: DBS3900 Configurations (Star/Cascade)	9
Exhibit 5: BSBC Configuration for LTE.....	9
Exhibit 6: BBU3900 Basic Configuration for LTE with cards.....	9
Exhibit 7: BBU3900 Typical 3x20MHz 2T2R Configuration for LTE with cards	10
Exhibit 8: BSBC Chassis, Front View	11
Exhibit 9: BSBC Chassis, Top View	12
Exhibit 10: BSBC Chassis, Bottom View	12
Exhibit 11: BSBC Chassis, Left View	13
Exhibit 12: BSBC Chassis, Right View	13
Exhibit 13 : BSBC Chassis, Back View.....	14
Exhibit 14: BSBC Chassis, Back View with Back plate Cover Removed	14
Exhibit 15: Backplane Connector PCB, Top View	15
Exhibit 16: Backplane Connector PCB, Bottom View	15
Exhibit 17: Backplane Connector Component Diagram, Top View	16
Exhibit 18: Fan Unit Panel Identification.....	18
Exhibit 19: Fan Unit, Top View.....	18
Exhibit 20: Fan Unit, Bottom View.....	19
Exhibit 21: Fan Unit, Right Side View.....	19
Exhibit 22: Fan Unit, Left Side View.....	19
Exhibit 23: Fan Unit Component Diagram.....	20
Exhibit 24: Fan Unit Cable Diagram.....	20
Exhibit 25: Fan Unit PCB, Top View, Component Diagram	21
Exhibit 26: Fan Unit PCB, Bottom View. Component Diagram	22
Exhibit 27: UPEU Panel Identification.....	24
Exhibit 28: UPEUc, Top View	25
Exhibit 29: UPEUc, Bottom View	25
Exhibit 30: UPEUc, Side View	25
Exhibit 31: UPEU Ethernet PCB, Top View	26
Exhibit 32: UPEU Ethernet PCB, Bottom View, Component Diagram.....	26
Exhibit 33: UPEU Main PCB with Heatsink (Top) and without (Bottom).....	28
Exhibit 34: UPEU Main PCB, Top View	29
Exhibit 35: UPEU Main PCB, Bottom View	29
Exhibit 36: UPEU Main PCB Area A Component Diagram	30
Exhibit 37: UPEU Main PCB Area B Component Diagram	30
Exhibit 38: BBU3900 Basic Configuration (3x20MHz 2T2R) for LTE with LBBPc card.....	33
Exhibit 39: BBU3900 Basic Configuration (3x20MHz 2T2R) for LTE with LBBPb cards.....	33
Exhibit 40: LMPT Panel Identification	34
Exhibit 41: Working Principle of the LMPT Unit	34
Exhibit 42: LMPT Board, Top View	35
Exhibit 43: LMPTb System Block Diagram	36
Exhibit 44: LMPT Board Top View Analysis Map.....	37
Exhibit 45: LMPT Board Top View Component Diagram	37
Exhibit 46: LMPT Board Top View Area A Component Diagram.....	38
Exhibit 47: Area B GPS Processing Daughter Card, Top View Component Diagram	38
Exhibit 48: Area B GPS Processing Daughter Card, Bottom View Component Diagram	39
Exhibit 49: External GPS Cable	39
Exhibit 50: Internal GPS Cable.....	40
Exhibit 51: LMPT Area C Daughter Card Top View Component Diagram	40
Exhibit 52: LMPT Area C Daughter Card Bottom View Component Diagram	41
Exhibit 53: LMPT Board Bottom View Component Diagram	42
Exhibit 54: LMPT Faceplate	42
Exhibit 55: LBBPb Panel Identification	54
Exhibit 56: LBBPc Panel Identification.....	54
Exhibit 57: LBBPd Panel Identification	54
Exhibit 58: LBBPc System Block Diagram.....	55
Exhibit 59: LBBP Board, Top View	56
Exhibit 60: LBBP Top View Component Diagram	56

Exhibit 61: LBBP Bottom View Component Diagram 57
Exhibit 62: LBBP Faceplate..... 57
Exhibit 63: Passive Component Case Size Distribution 61
Exhibit 64: Identified Passive Component Market Share by Vendor 64
Exhibit 65: Active Semiconductor Component Share..... 65
Exhibit 66: High Pin Count IC vs. Discretes 67
Exhibit 67: Active Semiconductor Market Share by Vendor 67
Exhibit 68: High Pin Count (64+) Active Semiconductor Market Share by Vendor 68